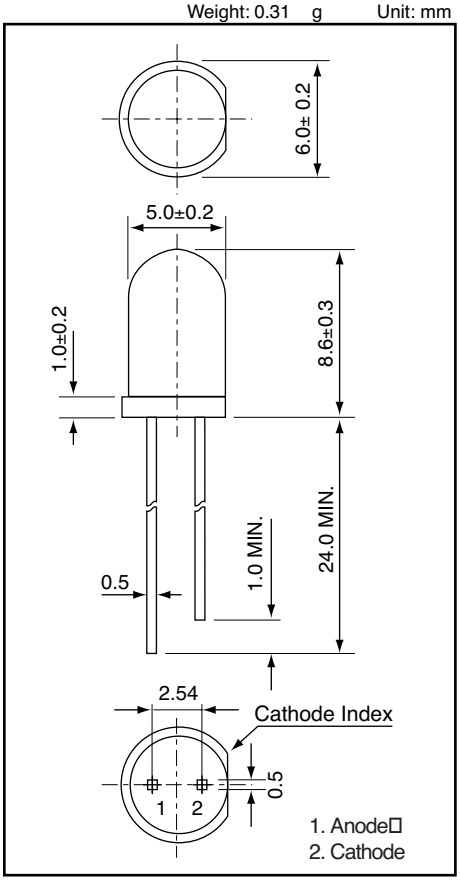
Weight: 0.31 g Unit: mm



AND157HSP

InGaAlP High Brightness Soft Red Light Emission

5mm (T1-3/4) Package

Features

- Peak wavelength (λp=632 nm) high bright emission
- All plastic mold type, clear colorless lens
- Low drive current: 1 ~ 20 mA DC
- Excellent On-Off contrast ratio
- Fast response time, capable of pulse operation
- High power intensity – suitable for outdoor usage
- High reliability, storage temp. –40 ~ 85°C

Maximum Ratings (T_a = 25°C)

Characteristics	Symbol	Rating	Unit
Forward Current	I_F	50	mA
Reverse Voltage	V_R	5	V
Power Dissipation	P_D	125	mW
Operating Temperature Range	T_{Opr}	-40 to 85	°C
Storage Temperature Range	T_{Stg}	-40 to 100	°C
Peak Forward Current Duty 1/ 10, Pulse Width 10 ms	IFP	160	mA

Electro-Optical Characteristics (T_a = 25°C)

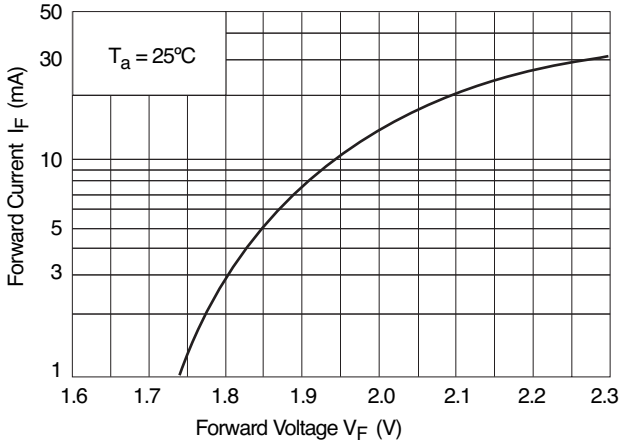
Characteristics	Symbol	Test Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	V_F	I_F = 20 mA	–	2.0	2.6	V
Reverse Current	I_R	V_R = 5 V	–	–	50	μA
Luminous Intensity	I_V	I_F = 20 mA	4,500	5,650	–	mcd
Peak Emission Wavelength	I_P	I_F = 20 mA	–	632	–	nm
Spectral Line Half Width	λΔ	I_F = 20 mA	–	20	–	nm
Dominant Wavelength	λd	I_F = 20 mA	–	615	–	nm
Full Viewing Angle	2 θ 1/2	I_V = 1/2 Peak	–	30	–	degree

Precaution

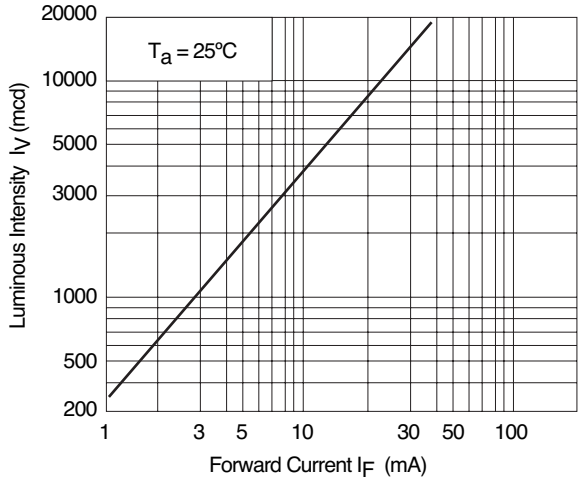
Please be careful of the following:

1. Soldering temperature: 260 C max., Soldering time: 5 sec. max.
   Soldering portion of lead: up to 1.6 mm from the body of the device
2. Reflow solder: recommended condition is as follows:

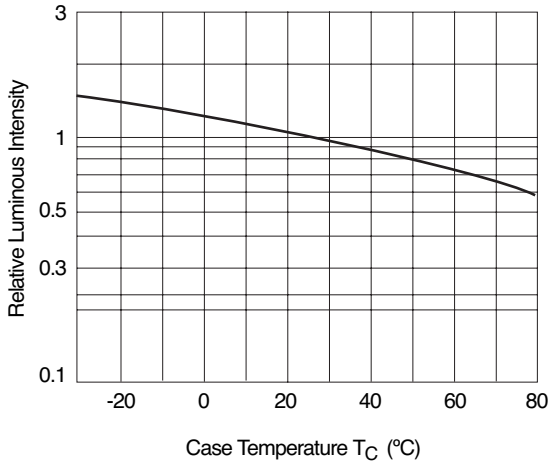
$I_F - V_F$



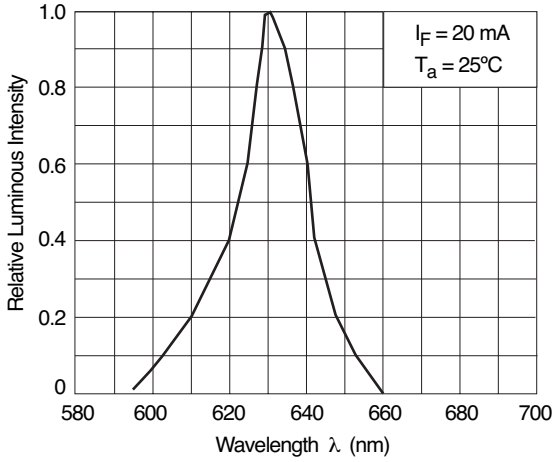
$I_V - I_F$



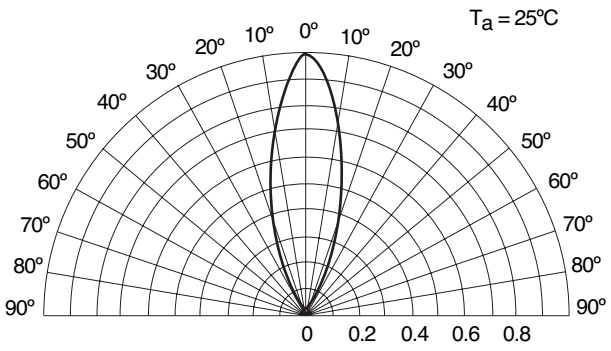
$I_V - T_C$



Relative Luminous Intensity – Wavelength



Radiation Pattern



$I_F - T_a$